Jetting Die Attach, Ablebond 84-3J

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The goal was to test the jettability of this material for various packaging applications, including stacked die. Jetting gives the user the advantages of optimizing die attach patterns and up to a 5X speed advantage over needle dispensing. Screen printing is not an option for this type of package.

Settings Summary

Platform	X-1020
Jet/Pump/Valve	DJ-9000
Fluid Type	Die attach / component attach (non-conductive)
Fluid Manufacturer & Product number	Ablebond 84-3J
Fluid Details	20,000 cps electrically insulating epoxy
Hardware Configuration	Needle: 0.063 in. (pn 7200580-24) Nozzle: 8/4 unitized (pn 721384-24)
Fluid Pressure	8 psi
Nozzle Temperature	45 C
Dispense Height	0.75 mm
Valve on / off	3 ms / 3 ms
Micrometer Setting	10
Substrate Temp	Room Temperature
Substrate	Glass Slide
Applications Development	Lihn Rolland

Results Summary

Dot diameter 0.6 mm, approximately 100 microns tall.
20,000 dots with no accumulation.